TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ( $\pi$ -MOSV)

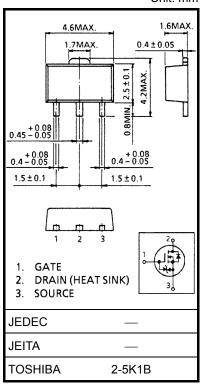
# 2SK2549

# DC–DC Converter, Relay Drive and Motor Drive Applications

- 2.5-V gate drive
- Low drain-source ON resistance  $: R_{DS}(ON) = 0.29 \Omega$  (typ.)
- High forward transfer admittance  $\therefore$  |Y<sub>fs</sub>| = 3.0 S (typ.)
  - Low leakage current  $: I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 16 \ V)$
- Enhancement mode :  $V_{th} = 0.5 \sim 1.1 \text{ V} (V_{DS} = 10 \text{ V}, \text{ I}_D = 200 \text{ }\mu\text{A})$

#### Absolute Maximum Ratings (Ta = 25°C)

Characteris	tics	Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	16	V	
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)		V <sub>DGR</sub>	16	V	
Gate-source voltage		V <sub>GSS</sub>	±8	V	
Drain current	DC (Note 1)	۱ <sub>D</sub>	2	А	
	Pulse (Note 1)	I <sub>DP</sub>	6	~	
Drain power dissipation	1	PD	0.5	W	
Drain power dissipation (Note 2)		PD	1.5	W	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature ra	inge	T <sub>stg</sub>	-55~150	°C	



Weight: 0.05 g (typ.)

Note 1: Ensure that the channel temperature does not exceed 150°C. Note 2: Mounted on a ceramic substrate (25.4 mm × 25.4 mm × 0.8 mm)

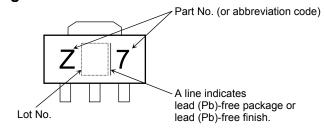
Note 3: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient	R <sub>th (ch−a)</sub>	250	°C / W

This transistor is an electrostatic-sensitive device. Please handle with caution.

## Marking



Unit: mm

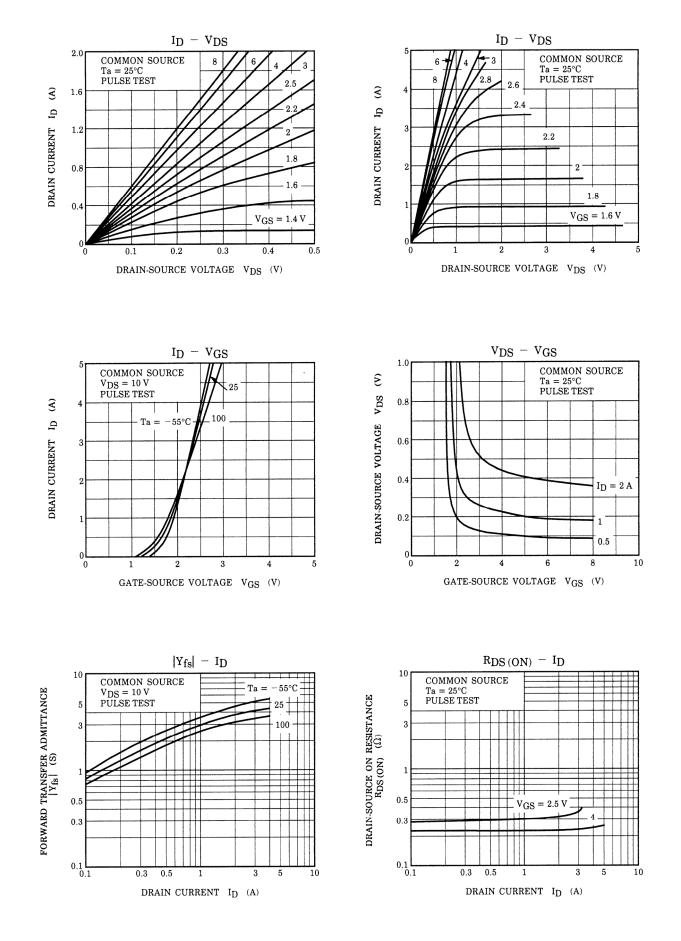
Electrical Characteristics (Ta = 25°C)

Charao	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	$V_{GS}$ = ±6.5 V, $V_{DS}$ = 0 V	_	_	±10	μA
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 16 V, V <sub>GS</sub> = 0 V			100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	16			V
Gate threshold	voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 200 μA	0.5	_	1.1	V
Drain-source ON resistance		R <sub>DS (ON)</sub>	V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 0.5 A		0.29	0.38	Ω
			V <sub>GS</sub> = 4 V, I <sub>D</sub> = 1 A	-	0.22	0.29	32
Forward transfe	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 A	1.5	3.0	—	S
Input capacitance	ce	C <sub>iss</sub>			260	_	
Reverse transfer capacitance		C <sub>rss</sub>	ss V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		34	_	pF
Output capacitance		C <sub>oss</sub>			103	_	
Switching time	Rise time	tr	$V_{GS} \stackrel{5}{}_{0} \stackrel{V}{V} \prod_{O \\ O \\ C \\ $	_	200	_	
	Turn-on time	t <sub>on</sub>		_	250	_	20
	Fall time	t <sub>f</sub>			300	—	ns
	Turn-off time	t <sub>off</sub>	Duty $\leq$ 1%, t <sub>w</sub> = 10 µs		800	_	
Total gate charge (Gate-source plus gate-drain)		Qg			5.0	_	nC
Gate-source charge		Q <sub>gs</sub>	V <sub>DD</sub> ≈ 16 V, V <sub>GS</sub> = 5 V, I <sub>D</sub> = 2 A	_	3.2	_	
Gate-drain ("miller") charge		Q <sub>gd</sub>	1		1.8	_	

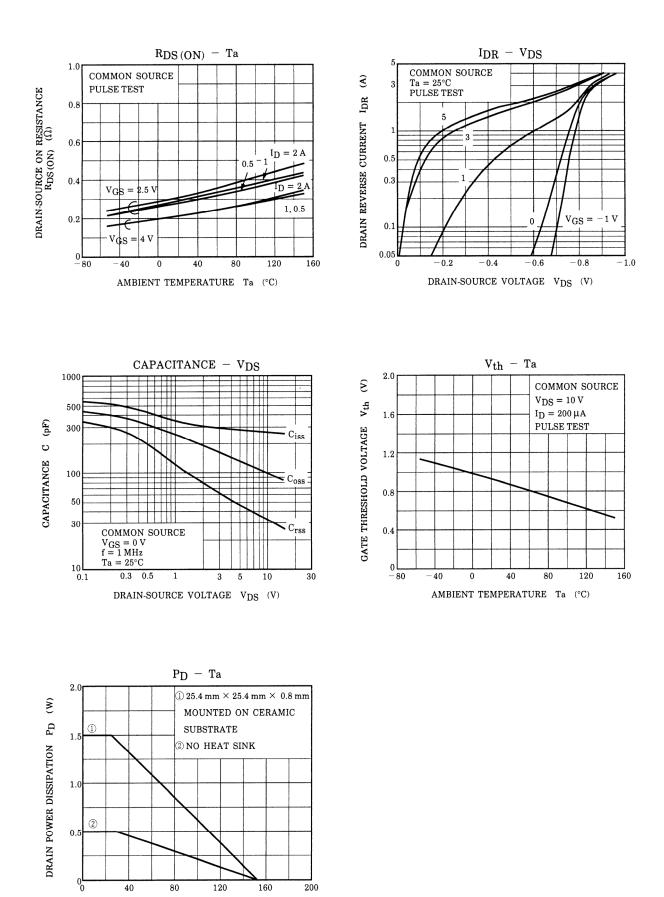
## Source–Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	—	_	_	2	А
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_		6	А
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 2 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 2 A, V <sub>GS</sub> = 0 V		220		ns
Reverse recovered charge	Q <sub>rr</sub>	dI <sub>DR</sub> / dt = 50 A / μs		0.32		μC

# **TOSHIBA**

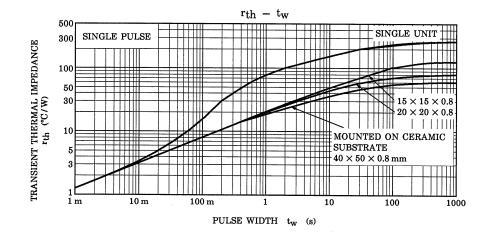


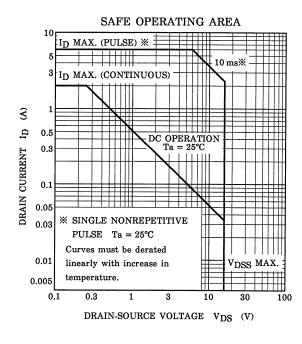
# **TOSHIBA**



AMBIENT TEMPERATURE Ta (°C)

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